



Product Change Notification

Change Notification #: 118125 - 00
Change Title: Select Intel® Thermal Solution BXTS13A,
Passive Thermal Solution BXSTS300P,
Passive Thermal Solution BXSTS300PNRW,
Passive/Active Combination Heat-Sink with
removable Fan BXSTS300C,
PCN 118125-00, Product Discontinuance,
End of Life
Date of Publication: March 11, 2021

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins:	March 11, 2021
Last Product Discontinuance Order Date:	October 1, 2021
Last Product Discontinuance Shipment Date:	December 1, 2021
Orders for Discontinued Products Become Non-Cancelable:	October 1, 2021

Description of Change to the Customer:

Market demand for the products listed in the "Products Affected/Intel Ordering Codes" tables below have shifted to other Intel products. The products identified in this notification will be discontinued and unavailable for additional orders after the "Last Product Discontinuance Order Date" (see "Key Milestones" above.)

Customer may purchase 3rd party alternate products listed in the Alternate Product Source table below.

Alternate Product Source

Intel® Discontinued Products		Foxconn Part Number (Alternate Products)	Foxconn Contact
Product Code	MM#		
BXSTS300P	958609	1A014QD00-PCY (single pack)	Yoyo Chen yoyo.hr.chen@foxconn.com (+86) 757-88021668 Ext 17653
BXSTS300PNRW	958610	1A21HKT00-RPA (single pack)	
BXSTS300C	958611	1A21BJ900-RPN (single pack) 1A21BJ900-RPC (bulk package)	
BXTS13A	937425	NA	

Customer Impact of Change and Recommended Action:

Products listed in the "Products Affected/Intel Ordering Codes" table should be managed in accordance with the "Key Milestones" listed above. The "Last Product Discontinuance Order Date" is the final day for customers who carry backlog to book the orders Intel has granted as of the "Orders are Non-Cancellable and Non-Returnable After" (NCNR) date. The "Orders are Non-Cancellable and Non-Returnable After" date applies to all remaining backlog and/or orders after the "Last Product Discontinuance Order Date." From date of PCN publication, interim booking and turn back deadlines or separate Letter Agreements will apply vs. the standard Corporate Assurance Process.

Customers who chose to purchase alternate products will be at sole discretion between the customer and Foxconn.

Please contact your local Intel Field Sales representative if you have any further questions about this End of Life notice.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Thermal Solution BXTS13A, Retail Box	BXTS13A	937425
Passive Thermal Solution BXSTS300P, Single	BXSTS300P	958609
Passive Thermal Solution BXSTS300PNRW, Single	BXSTS300PNRW	958610
Passive/Active Combination Heat-Sink with removable Fan BXSTS300C, Single	BXSTS300C	958611

PCN Revision History:

Date of Revision:

March 11, 2021

Revision Number:

00

Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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